Single-Channel Transient Voltage Suppressor

Product Description

ON Semiconductor's ESD6116 is an *Application Specific Integrated Passive*^{\mathbb{M}} (ASIP^{\mathbb{M}}) component in a 2 x 2, 4-bump, 0.4 mm pitch, CSP form factor. This device is designed for:

- Transient Voltage Suppression
- Electrostatic Discharge Protection
- Electrical Overstress Protection

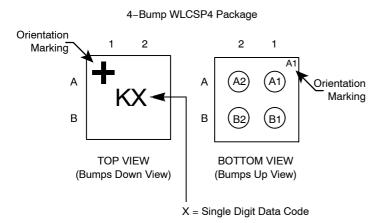
Features

- 4-Bump, 0.80 mm X 0.80 mm Footprint Chip Scale Package (CSP)
- These Devices are Pb-Free and are RoHS Compliant

Table 1. PIN DESCRIPTIONS

Pins	Description	
A1 and A2	TVS Channel	
B1 and B2	Device Ground	

PACKAGE / PINOUT DIAGRAMS





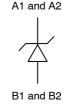
ON Semiconductor®

http://onsemi.com



WLCSP4 CASE 567CB

ELECTRICAL SCHEMATIC



MARKING DIAGRAM



K = ESD6116 X = Single Digit Data Code

ORDERING INFORMATION

Device	Package	Shipping [†]
ESD6116	WLCSP4 (Pb-Free)	10,000/Tape & Reel

+ For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

ESD6116

ELECTRICAL SPECIFICATIONS AND CONDITIONS

Table 2. PARAMETERS AND MAXIMUM ABSOLUTE OPERATING CONDITIONS

Parameter	Rating	Units
Storage Temperature Range	–55 to +150	°C
Operating Temperature Range	-30 to +85	°C
Failing to Nonconductive, I^2t (Maximum Ipp Value Using 10/1000 μs Pulse). (Notes 1 and 2)	100	A

The device must not burn to open-circuit, when the value is below maximum I_{PP}
This parameter is characterized at 25°C using an ON Semiconductor-specific test board.

Table 3. ELECTRICAL OPERATING CHARACTERISTICS (Note 3)

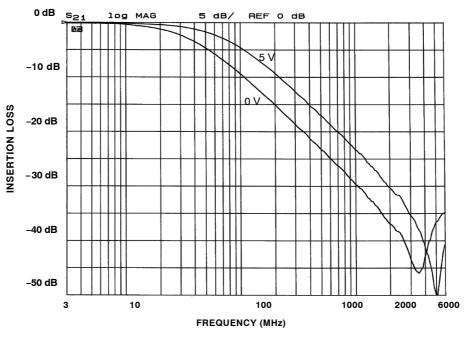
Symbol	Parameter	Conditions	Min	Тур	Max	Units
I _{OFF}	Stand-Off Quiescent Current	Stand-Off Voltage V _{OFF} = 10 V			500	nA
V_{BR}	Break Down Voltage	Break Down Current I _{BR} = 15 mA	16			V
V _{CL}	Clamping Voltage during Transient	Clamping Current I _{CL} = 1 A (Note 5)			20	V
V _F	Forward Voltage	Forward Current I _F = 850 mA			1.3	V
C _{L1}	Line Capacitance	V _{BIAS} = 0 V		172		pF
C _{L2}		$V_{BIAS} = 5 \text{ V}, \text{ T}_{A} = 25^{\circ}\text{C};$	66	83	100	pF
V _{ESD}	ESD Protection Peak Discharge Voltage at any Channel Input a) Contact Discharge per IEC 61000-4-2 Standard b) Air Discharge per IEC 61000-4-2 Standard	T _A = 25°C (Note 4)	±30 ±30			kV
	Minimum Attenuation Freq = 80 MHz – 1 Ghz Freq = 1 – 4 GHz	$R_{SOURCE} = R_{LOAD} = 50 \ \Omega$ $T_A = 25^{\circ}C$		8 20		dB

3. All parameters specified for $T_A = -30^{\circ}C$ to $85^{\circ}C$ unless otherwise noted. 4. Standard IEC 61000-4-2 with $C_{Discharge} = 150 \text{ pF}$, $R_{Discharge} = 330 \Omega$. 5. Transient: 8 x 20 µs current pulse.

ESD6116

RF CHARACTERISTICS

$T_A = 25^{\circ}C$, 50 Ω Environment

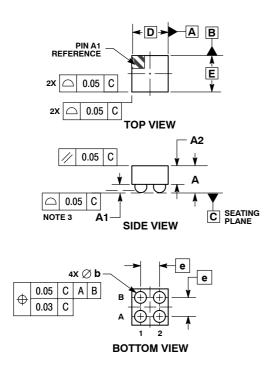




ESD6116

PACKAGE DIMENSIONS

WLCSP4, 0.8x0.8 CASE 567CB ISSUE O



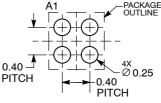
NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.

 CONTROLING DIMENSION: MILLIMETERS.
COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

9	CROWNS OF SOLDER E				
		MILLIMETERS			
	DIM	MIN	MAX		
	Α	0.57	0.63		
	A1	0.17	0.24		
	A2	0.41 REF			
	b	0.24	0.29		
	D	D 0.80 BSC			
	Е	E 0.80 BSC e 0.40 BSC			
	е				

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

Application Specific Integrated Passive is a trademark of Semiconductor Components Industries, LLC (SCILLC).

ON Semiconductor and use registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death agsociated with such unintended or unauthorized use payers that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunit//Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor P.O. Box 5163, Denver, Colorado 80217 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com N. American Technical Support: 800–282–9855 Toll Free USA/Canada Europe, Middle East and Africa Technical Support:

Phone: 421 33 790 2910 Japan Customer Focus Center Phone: 81–3–5817–1050

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative